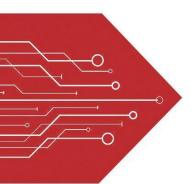
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet





DFN1006

FEATURES

♦ IEC61000-4-2 (ESD) ±8kV (Contact)

±15kV (Air)

♦ IEC61000-4-4 (EFT) 40A (5/50ηs)

♦ IEC61000-4-5 (Lighting) 3A (8/20µs)

♦ 100 Watts Peak Pulse Power (tp=8/20µs)

♦ Working voltages : 24V

♦ Low clamping voltage

♦ Low leakage current

MACHANICAL DATA

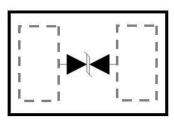
♦ DFN1006 package

♦ Flammability Rating: UL 94V-0

♦ Packaging: Tape and Reel

♦ Reel size: 7 inch

PIN CONFIGURATION



APPLICATIONS

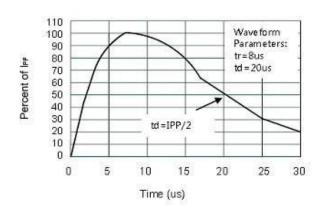
- ♦ Serial and Parallel Ports
- ♦ Notebooks, Desktops, Servers
- ♦ Projection TV
- ♦ Cellular handsets and accessories
- ♦ Portable instrumentation
- ♦ Peripherals

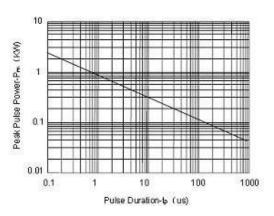
ABSOLUTE MAXIMUM RATING					
Symbol	Parameter	Value	Units		
V	ESD per IEC 61000-4-2 (Contact)	±8	kV		
V _{ESD}	ESD per IEC 61000-4-2 (Air)	±15			
P _{PP}	Peak Pulse Power (8/20μs)	150	W		
T _{OPT}	Operating Temperature	-55 ~ +125	°C		
T _{STG}	Storage Temperature	-55 ~ +150	°C		
T _L	Lead Soldering Temperature	260 (10 sec.)	°C		



ELECTRICAL CHARACTERISTICS (Tamb=25°C)						
Symbol	Parameter	Test Condition	Min	Тур	Max	Units
V _{RWM}	Reverse Working Voltage				24	V
V_{BR}	Reverse Breakdown Voltage	I _T = 1mA	26		32	V
I _R	Reverse Leakage Current	$V_{RWM} = 24V$			1	μΑ
V _{C1}	Clamping Voltage 1	$I_{PP} = 1A, t_p = 8/20 \mu s$			40	V
V _{C2}	Clamping Voltage 2	$I_{PP} = 3A, t_p = 8/20 \mu s$			50	٧
Сл	Junction Capacitance	V _R = 0V, f = 1MHz		8		pF

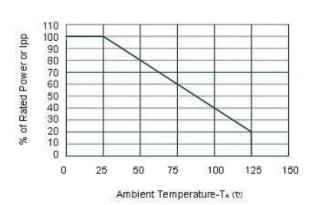
ELECTRICAL CHARACTERISTICS CURVE



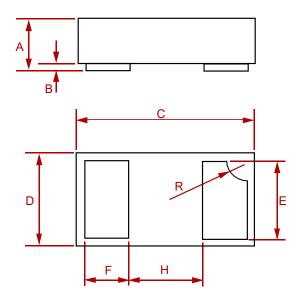


Pulse Waveform

Non-Repetitive Peak Pulse Power vs. Pulse Time

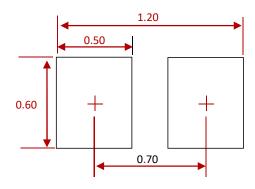


PACKAGE MECHANICAL DATA



Dim	Inches		Millimeters		
	MIN	MAX	MIN	MAX	
Α	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.015Typ.		0.40Тур.		
R	0.001	0.005	0.05	0.15	

Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
D24V0L1B2LPS-7B	DFN1006	10000



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